

## ADC0844/ADC0848 8-Bit $\mu$ P Compatible A/D Converters with Multiplexer Options

Check for Samples: [ADC0844](#), [ADC0848](#)

### FEATURES

- Easy interface to all microprocessors
- Operates ratiometrically or with 5 V<sub>DC</sub> voltage reference
- No zero or full-scale adjust required
- 4-channel or 8-channel multiplexer with
- address logic
- Internal clock
- 0V to 5V input range with single 5V power supply
- 0.3" standard width 20-pin or 24-pin DIP
- 28 Pin Molded Chip Carrier Package

### DESCRIPTION

The ADC0844 and ADC0848 are CMOS 8-bit successive approximation A/D converters with versatile analog input multiplexers. The 4-channel or 8-channel multiplexers can be software configured for single-ended, differential or pseudo-differential modes of operation.

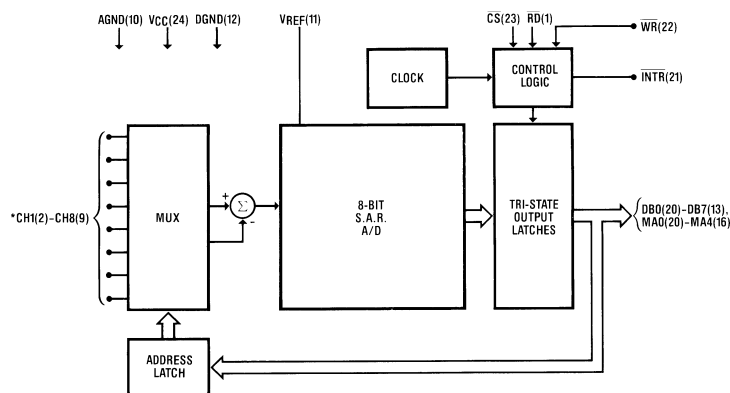
The differential mode provides low frequency input common mode rejection and allows offsetting the analog range of the converter. In addition, the A/D's reference can be adjusted enabling the conversion of reduced analog ranges with 8-bit resolution.

The A/Ds are designed to operate from the control bus of a wide variety of microprocessors. TRI-STATE output latches that directly drive the data bus permit the A/Ds to be configured as memory locations or I/O devices to the microprocessor with no interface logic necessary.

**Table 1. Key Specifications**

	VALUE	UNIT
Resolution	8	Bits
Total Unadjusted Error	$\pm \frac{1}{2}$ LSB and $\pm 1$	LSB
Single Supply	5 V <sub>DC</sub>	
Low Power	15	mW
Conversion Time	40 $\mu$ s	

### Block Diagram



\* ADC0848 shown in DIP Package CH5-CH8 not included on the ADC0844



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## Connection Diagram

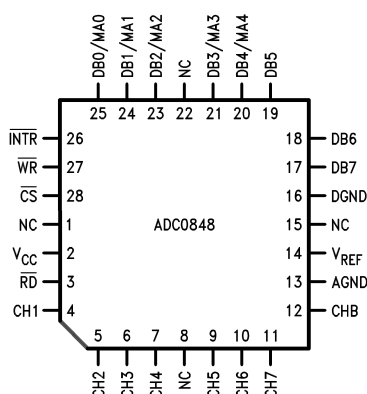


Figure 1. Molded Chip Carrier Package (Top View)

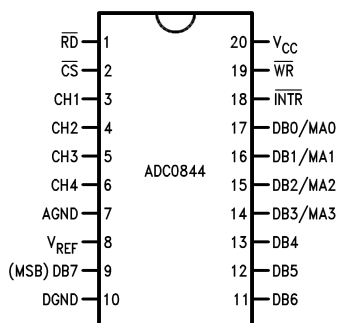


Figure 2. Dual-In-Line Package (Top View)

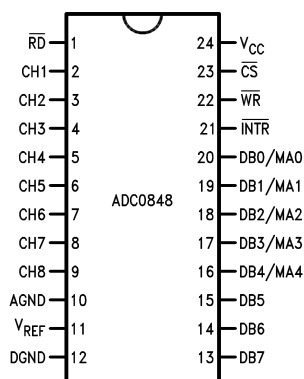


Figure 3. Dual-In-Line Package (Top View)



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### Absolute Maximum Ratings <sup>(1) (2)</sup>

Supply Voltage ( $V_{CC}$ )	6.5V
Voltage	
Logic Control Inputs	–0.3V to +15V
At Other Inputs and Outputs	–0.3V to $V_{CC}+0.3V$
Input Current at Any Pin <sup>(3)</sup>	5 mA
Package Input Current <sup>(3)</sup>	20 mA
Storage Temperature	–65°C to +150°C
Package Dissipation at $T_A=25^{\circ}\text{C}$	875 mW
ESD Susceptibility <sup>(4)</sup>	800V
Lead Temperature (Soldering, 10 seconds)	
Dual-In-Line Package (Plastic)	260°C
Dual-In-Line Package (Ceramic)	300°C
Molded Chip Carrier Package	
Vapor Phase (60 seconds)	215°C
Infrared (15 seconds)	220°C

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its specified operating conditions.
- (2) All voltages are measured with respect to the ground pins.
- (3) When the input voltage ( $V_{IN}$ ) at any pin exceeds the power supply rails ( $V_{IN} < V^-$  or  $V_{IN} > V^+$ ) the absolute value of the current at that pin should be limited to 5 mA or less. The 20 mA package input current limits the number of pins that can exceed the power supply boundaries with a 5 mA current limit to four.
- (4) Human body model, 100 pF discharged through a 1.5 k $\Omega$  resistor.

### Operating Conditions <sup>(1) (2)</sup>

Supply Voltage ( $V_{CC}$ )	4.5 $V_{DC}$ to 6.0 $V_{DC}$
Temperature Range	$T_{MIN} \leq T_A \leq T_{MAX}$
ADC0844CCN, ADC0848BCN, ADC0848CCN	$0^{\circ}\text{C} \leq T_A \leq 70^{\circ}\text{C}$
ADC0844BCJ <sup>(3)</sup> , ADC0844CCJ <sup>(3)</sup> , ADC0848BCV, ADC0848CCV	$-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its specified operating conditions.
- (2) All voltages are measured with respect to the ground pins.
- (3) Product/package combination obsolete; shown for reference only.

## Electrical Characteristics

The following specifications apply for  $V_{CC} = 5 V_{DC}$  unless otherwise specified. **Boldface limits apply from  $T_{MIN}$  to  $T_{MAX}$** ; all other limits  $T_A = T_j = 25^\circ C$ .

Parameter	Conditions	ADC0844BCJ <sup>(1)</sup> ADC0844CCJ <sup>(1)</sup>			ADC0844CCN ADC0848BCN, ADC0848CCN ADC0848BCV, ADC0848CCV			Limits Units
		Typ (2)	Tested Limit (3)	Design Limit (4)	Typ (2)	Tested Limit (3)	Design Limit (4)	
CONVERTER AND MULTIPLEXER CHARACTERISTICS								
Maximum Total Unadjusted Error	V <sub>REF</sub> =5.00 V <sub>DC</sub> (5)							
ADC0844BCN, ADC0848BCN, BCV						±½	±½	LSB
ADC0844CCN, ADC0848CCN, CCV						±1	±1	LSB
ADC0844CCJ <sup>(1)</sup>			±1					LSB
Minimum Reference Input Resistance		2.4	1.1		2.4	1.2	1.1	kΩ
Maximum Reference Input Resistance		2.4	5.9		2.4	5.4	5.9	kΩ
Maximum Common-Mode Input Voltage	(6)		V <sub>CC</sub> +0.05			V <sub>CC</sub> +0.05	V <sub>CC</sub> +0.05	V
Minimum Common-Mode Input Voltage	(6)		GND-0.05			GND-0.05	GND-0.05	V
DC Common-Mode Error	Differential Mode	±1/16	±¼		±1/16	±¼	±¼	LSB
Power Supply Sensitivity	V <sub>CC</sub> =5V±5% (7)	±1/16	±⅛		±1/16	±⅛	±⅛	LSB
Off Channel Leakage Current	On Channel=5V, Off Channel=0V		-1			-0.1	-1	μA
	On Channel=0V, Off Channel=5V		1			0.1	1	μA
DIGITAL AND DC CHARACTERISTICS								
V <sub>IN(1)</sub> , Logical “1” Input Voltage (Min)	V <sub>CC</sub> =5.25V		2.0			2.0	2.0	V
V <sub>IN(0)</sub> , Logical “0” Input Voltage (Max)	V <sub>CC</sub> =4.75V		0.8			0.8	0.8	V
I <sub>IN(1)</sub> , Logical “1” Input Current (Max)	V <sub>IN</sub> =5.0V	0.005	1		0.005		1	μA
I <sub>IN(0)</sub> , Logical “0” Input Current (Max)	V <sub>IN</sub> =0V	-0.005	-1		-0.005		-1	μA
V <sub>OUT(1)</sub> , Logical “1” Output Voltage (Min)	V <sub>CC</sub> =4.75V, I <sub>OUT</sub> =-360 μA		2.4			2.8	2.4	V
	I <sub>OUT</sub> =-10 μA		4.5			4.6	4.5	V
								V
V <sub>OUT(0)</sub> , Logical “0” Output Voltage (Max)	V <sub>CC</sub> =4.75V, I <sub>OUT</sub> =1.6 mA		0.4			0.34	0.4	V
I <sub>OUT</sub> , TRI-STATE Output Current (Max)	V <sub>OUT</sub> =0V	-0.01	-3		-0.01	-0.3	-3	μA
	V <sub>OUT</sub> =5V	0.01	3		0.01	0.3	3	μA
I <sub>SOURCE</sub> , Output Source Current (Min)	V <sub>OUT</sub> =0V	-14	-6.5		-14	-7.5	-6.5	mA
I <sub>SINK</sub> , Output Sink Current (Min)	V <sub>OUT</sub> =V <sub>CC</sub>	16	8.0		16	9.0	8.0	mA

(1) This product/package combination is obsolete. Shown for reference only.

(2) Typical figures are at  $25^\circ C$  and represent most likely parametric norm.

(3) Tested limits are guaranteed to National's AOQL (Average Outgoing Quality Level).

(4) Design limits are guaranteed by not 100% tested. These limits are not used to calculate outgoing quality levels.

(5) Total unadjusted error includes offset, full-scale, linearity, and multiplexer error.

(6) For  $V_{IN(-)} \geq V_{IN(+)}$  the digital output code will be 0000 0000. Two on-chip diodes are tied to each analog input, which will forward-conduct for analog input voltages one diode drop below ground or one diode drop greater than  $V_{CC}$  supply. Be careful during testing at low  $V_{CC}$  levels (4.5V), as high level analog inputs (5V) can cause this input diode to conduct, especially at elevated temperatures, and cause errors for analog inputs near full-scale. The spec allows 50 mV forward bias of either diode. This means that as long as the analog  $V_{IN}$  does not exceed the supply voltage by more than 50 mV, the output code will be correct. To achieve an absolute 0  $V_{DC}$  to 5  $V_{DC}$  input voltage range will therefore require a minimum supply voltage of 4.950  $V_{DC}$  over temperature variations, initial tolerance and loading.

(7) Off channel leakage current is measured after the channel selection.

## Electrical Characteristics (continued)

The following specifications apply for  $V_{CC} = 5 V_{DC}$  unless otherwise specified. **Boldface limits apply from  $T_{MIN}$  to  $T_{MAX}$** ; all other limits  $T_A = T_j = 25^{\circ}C$ .

Parameter	Conditions	ADC0844BCJ <sup>(1)</sup> ADC0844CCJ <sup>(1)</sup>			ADC0844CCN ADC0848BCN, ADC0848CCN ADC0848BCV, ADC0848CCV			Limit Units
		Typ (2)	Tested Limit (3)	Design Limit (4)	Typ (2)	Tested Limit (3)	Design Limit (4)	
$I_{CC}$ , Supply Current (Max)	$\overline{CS} = 1$ , $V_{REF}$ Open	1	<b>2.5</b>		1	2.3	<b>2.5</b>	mA

## AC Electrical Characteristics

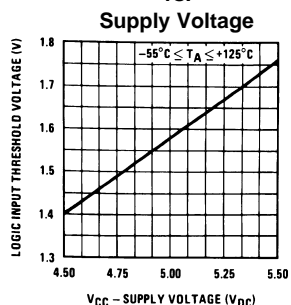
The following specifications apply for  $V_{CC} = 5V_{DC}$ ,  $t_r = t_f = 10$  ns unless otherwise specified. **Boldface limits apply from  $T_{MIN}$  to  $T_{MAX}$** ; all other limits  $T_A = T_J = 25^\circ C$ .

Parameter	Conditions	Typ <sup>(1)</sup>	Tested Limit <sup>(2)</sup>	Design Limit <sup>(3)</sup>	Units
$t_C$ , Maximum Conversion Time (See Graph)		30	40	<b>60</b>	$\mu s$
$t_{W(\overline{WR})}$ , Minimum $\overline{WR}$ Pulse Width	<sup>(4)</sup>	50	150		ns
$t_{ACC}$ , Maximum Access Time (Delay from Falling Edge of $\overline{RD}$ to Output Data Valid)	$C_L = 100$ pF <sup>(4)</sup>	145		225	ns
$t_{1H}$ , $t_{0H}$ , TRI-STATE Control (Maximum Delay from Rising Edge of $\overline{RD}$ to Hi-Z State)	$C_L = 10$ pF, $R_L = 10k$ <sup>(4)</sup>	125		200	ns
$t_{WL}$ , $t_{RL}$ , Maximum Delay from Falling Edge of $\overline{WR}$ or $\overline{RD}$ to Reset of INTR	<sup>(4)</sup>	200	400		ns
$t_{DS}$ , Minimum Data Set-Up Time	<sup>(4)</sup>	50	100		ns
$t_{DH}$ , Minimum Data Hold Time	<sup>(4)</sup>	0	50		ns
$C_{IN}$ , Capacitance of Logic Inputs		5			pF
$C_{OUT}$ , Capacitance of Logic Outputs		5			pF

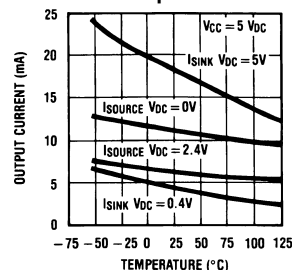
- (1) Typical figures are at  $25^\circ C$  and represent most likely parametric norm.
- (2) Tested limits are guaranteed to National's AOQL (Average Outgoing Quality Level).
- (3) Design limits are guaranteed by not 100% tested. These limits are not used to calculate outgoing quality levels.
- (4) The temperature coefficient is  $0.3\%/^\circ C$ .

## Typical Performance Characteristics

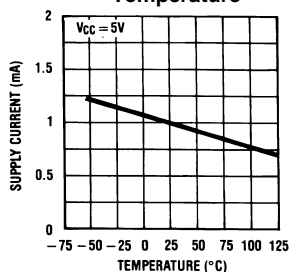
**Logic Input Threshold  
Voltage  
vs.  
Supply Voltage**



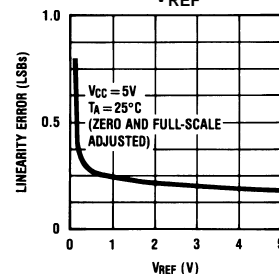
**Output Current vs.  
Temperature**



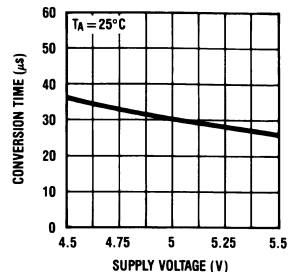
**Power Supply Current vs.  
Temperature**



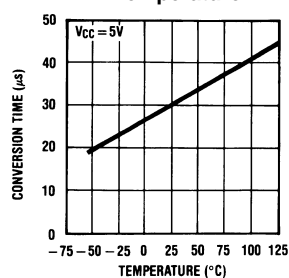
**Linearity Error  
vs.  
VREF**



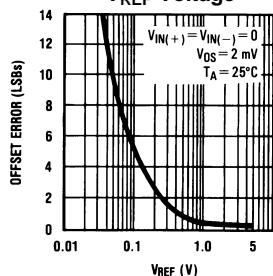
**Conversion Time  
vs.  
VSUPPLY**



**Conversion Time vs.  
Temperature**

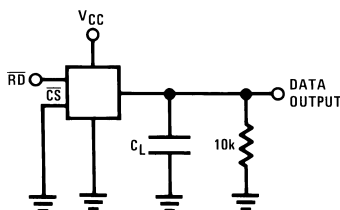


**Unadjusted Offset Error vs.  
VREF Voltage**

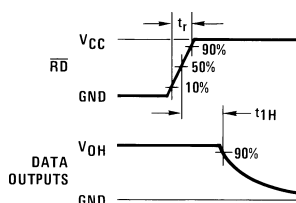


## TRI-STATE Test Circuits and Waveforms

**Figure 4.  $t_{1H}$**

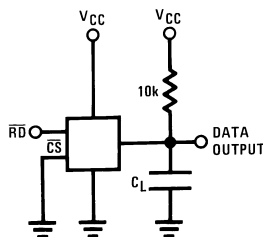


**Figure 5.  $t_{1H}$ ,  $C_L = 10\text{ pF}$**

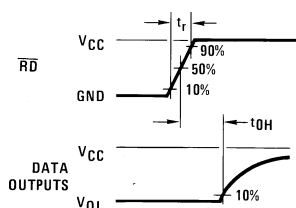


$t_r = 20\text{ ns}$

**Figure 6.  $t_{0H}$**

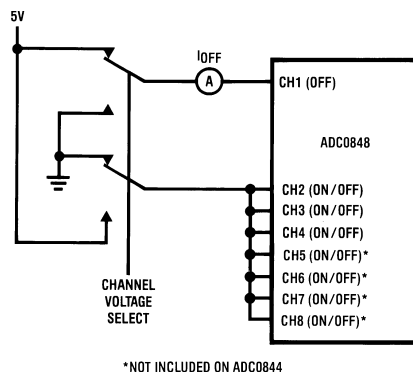


**Figure 7.  $t_{0H}$ ,  $C_L = 10\text{ pF}$**



$t_r = 20\text{ ns}$

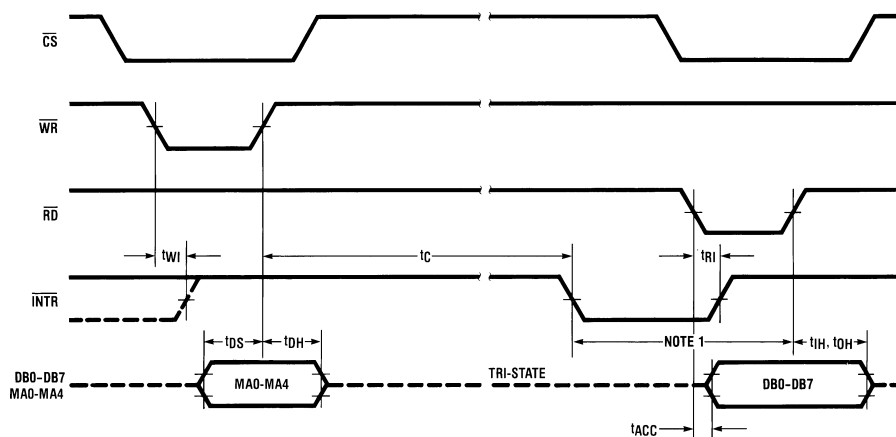
## Leakage Current Test Circuit



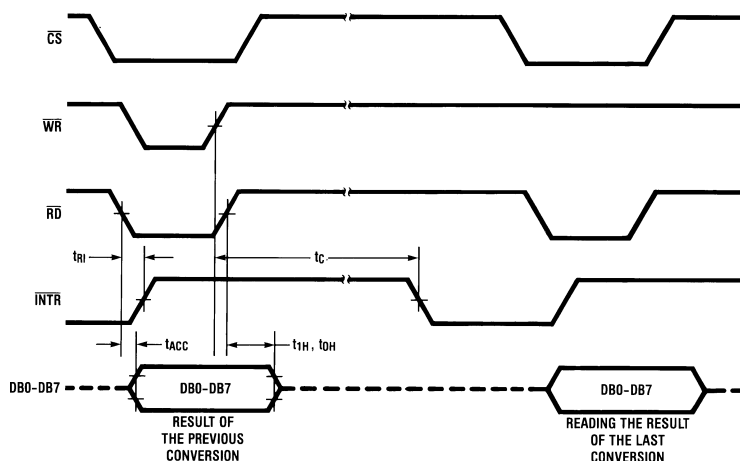
\*NOT INCLUDED ON ADC0844

## Timing Diagrams

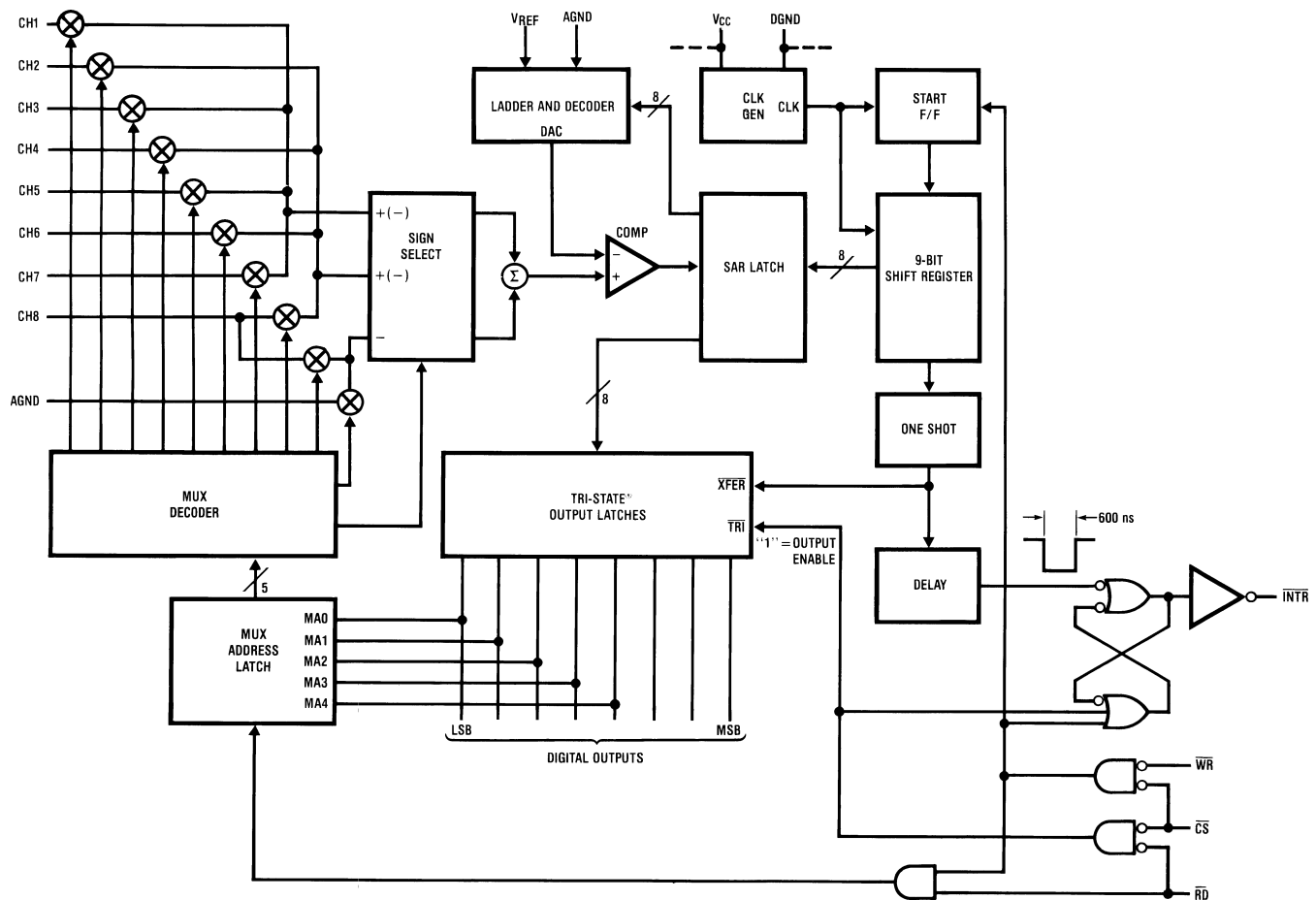
### Programming New Channel Configuration and Starting a Conversion



**Figure 8. Using the Previously Selected Channel Configuration and Starting a Conversion**



## ADC0848 Functional Block Diagram



## Functional Description

The ADC0844 and ADC0848 contain a 4-channel and 8-channel analog input multiplexer (MUX) respectively. Each MUX can be configured into one of three modes of operation differential, pseudo-differential, and single ended. These modes are discussed in the Applications Information Section. The specific mode is selected by loading the MUX address latch with the proper address (see [Table 2](#) and [Table 3](#)). Inputs to the MUX address latch (MA0-MA4) are common with data bus lines (DB0-DB4) and are enabled when the  $\overline{RD}$  line is high. A conversion is initiated via the  $\overline{CS}$  and  $\overline{WR}$  lines. If the data from a previous conversion is not read, the  $\overline{INTR}$  line will be low. The falling edge of  $\overline{WR}$  will reset the  $\overline{INTR}$  line high and ready the A/D for a conversion cycle. The rising edge of  $\overline{WR}$ , with  $\overline{RD}$  high, strobes the data on the MA0/DB0-MA4/DB4 inputs into the MUX address latch to select a new input configuration and start a conversion. If the  $\overline{RD}$  line is held low during the entire low period of  $\overline{WR}$  the previous MUX configuration is retained, and the data of the previous conversion is the output on lines DB0-DB7. After the conversion cycle ( $t_c \leq 40 \mu s$ ), which is set by the internal clock frequency, the digital data is transferred to the output latch and the  $\overline{INTR}$  is asserted low. Taking  $\overline{CS}$  and  $\overline{RD}$  low resets  $\overline{INTR}$  output high and outputs the conversion result on the data lines (DB0-DB7).

## Applications Information

### 1.0 MULTIPLEXER CONFIGURATION

The design of these converters utilizes a sampled-data comparator structure which allows a differential analog input to be converted by a successive approximation routine.

The actual voltage converted is always the difference between an assigned “+” input terminal and a “–” input terminal. The polarity of each input terminal of the pair being converted indicates which line the converter expects to be the most positive. If the assigned “+” input is less than the “–” input the converter responds with an all zeros output code.

A unique input multiplexing scheme has been utilized to provide multiple analog channels. The input channels can be software configured into three modes: differential, single ended, or pseudo-differential. Figure 9 shows the three modes using the 4-channel MUX ADC0844. The eight inputs of the ADC0848 can also be configured in any of the three modes. In the differential mode, the ADC0844 channel inputs are grouped in pairs, CH1 with CH2 and CH3 with CH4. The polarity assignment of each channel in the pair is interchangeable. The single-ended mode has CH1–CH4 assigned as the positive input with the negative input being the analog ground (AGND) of the device. Finally, in the pseudo-differential mode CH1–CH3 are positive inputs referenced to CH4 which is now a pseudo-ground. This pseudo-ground input can be set to any potential within the input common-mode range of the converter. The analog signal conditioning required in transducer-based data acquisition systems is significantly simplified with this type of input flexibility. One converter package can now handle ground referenced inputs and true differential inputs as well as signals with some arbitrary reference voltage.

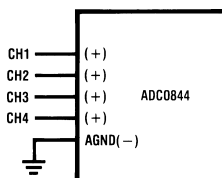
The analog input voltages for each channel can range from 50 mV below ground to 50 mV above  $V_{CC}$  (typically 5V) without degrading conversion accuracy.

**Table 2. ADC0844 MUX ADDRESSING<sup>(1)</sup>**

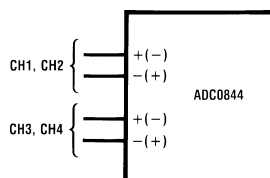
MUX Address				$\overline{CS}$	$\overline{WR}$	$\overline{RD}$	Channel#					MUX Mode
MA3	MA2	MA1	MA0				CH1	CH2	CH3	CH4	AGND	
X	L	L	L	L		H	+	–				Differential
X	L	L	H	L	NP	H	–	+				
X	L	H	L	L		H			+	–		
X	L	H	H	L		H			–	+		
L	H	L	L	L		H	+				–	Single-Ended
L	H	L	H	L	NP	H		+			–	
L	H	H	L	L		H			+		–	
L	H	H	H	L		H				+	–	
H	H	L	L	L		H	+			–		Pseudo- Differential
H	H	L	H	L	NP	H		+		–		
H	H	H	L	L		H			+	–		
X	X	X	X	L	NP	L	Previous Channel Configuration					

(1) X = don't care, NP = negative pulse

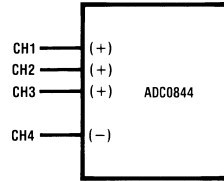
#### 4 Single-Ended



#### 2 Differential



### 3 Pseudo-Differential



### Combined

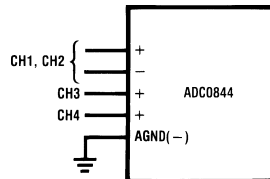


Figure 9. Analog Input Multiplexer Options

## 2.0 REFERENCE CONSIDERATIONS

The voltage applied to the reference input of these converters defines the voltage span of the analog input (the difference between  $V_{IN(MAX)}$  and  $V_{IN(MIN)}$ ) over which the 256 possible output codes apply. The devices can be used in either ratiometric applications or in systems requiring absolute accuracy. The reference pin must be connected to a voltage source capable of driving the minimum reference input resistance of 1.1 k $\Omega$ . This pin is the top of a resistor divider string used for the successive approximation conversion.

In a ratiometric system (Figure 10a), the analog input voltage is proportional to the voltage used for the A/D reference. This voltage is typically the system power supply, so the  $V_{REF}$  pin can be tied to  $V_{CC}$ . This technique relaxes the stability requirements of the system reference as the analog input and A/D reference move together maintaining the same output code for a given input condition. For absolute accuracy (Figure 10b), where the analog input varies between very specific voltage limits, the reference pin can be biased with a time and temperature stable voltage source. The LM385 and LM336 reference diodes are good low current devices to use with these converters.

The maximum value of the reference is limited to the  $V_{CC}$  supply voltage. The minimum value, however, can be quite small (see Typical Performance Characteristics) to allow direct conversions of transducer outputs providing less than a 5V output span. Particular care must be taken with regard to noise pickup, circuit layout and system error voltage sources when operating with a reduced span due to the increased sensitivity of the converter (1 LSB equals  $V_{REF}/256$ ).

## 3.0 THE ANALOG INPUTS

### 3.1 Analog Differential Voltage Inputs and Common-Mode Rejection

The differential input of these converters actually reduces the effects of common-mode input noise, a signal common to both selected “+” and “-” inputs for a conversion (60 Hz is most typical). The time interval between sampling the “+” input and then the “-” inputs is  $\frac{1}{2}$  of a clock period. The change in the common-mode voltage during this short time interval can cause conversion errors. For a sinusoidal common-mode signal this error is:

$$V_{ERROR(MAX)} = V_{peak} (2\pi f_{CM}) \times 0.5 \times \left( \frac{t_C}{8} \right)$$

where  $f_{CM}$  is the frequency of the common-mode signal,  $V_{peak}$  is its peak voltage value and  $t_C$  is the conversion time.

For a 60 Hz common-mode signal to generate a  $\frac{1}{4}$  LSB error ( $\approx 5$  mV) with the converter running at 40  $\mu$ S, its peak value would have to be 5.43V. This large a common-mode signal is much greater than that generally found in a well designed data acquisition system.

**Table 3. ADC0848 MUX Addressing<sup>(1)</sup>**

MUX Address					$\overline{CS}$	$\overline{WR}$	$\overline{RD}$	Channel									MUX Mode
MA4	MA3	MA2	MA1	MA0				CH1	CH2	CH3	CH4	CH5	CH6	CH7	CH8	AGND	
X	L	L	L	L	L		H	+	-								Differential
X	L	L	L	H	L		H	-	+								
X	L	L	H	L	L		H			+	-						
X	L	L	H	H	L	NP	H			-	+						
X	L	H	L	L	L		H					+	-				
X	L	H	L	H	L		H					-	+				
X	L	H	H	L	L		H							+	-		
X	L	H	H	H	L		H							-	+		
L	H	L	L	L	L		H	+								-	Single-Ended
L	H	L	L	H	L		H		+							-	
L	H	L	H	L	L		H			+						-	
L	H	L	H	H	L	NP	H				+					-	
L	H	H	L	L	L		H					+				-	
L	H	H	L	H	L		H						+			-	
L	H	H	H	L	L		H							+		-	
L	H	H	H	H	L		H								+	-	
H	H	L	L	L	L		H	+								-	Pseudo-Differential
H	H	L	L	H	L		H		+							-	
H	H	L	H	L	L		H			+						-	
H	H	L	H	H	L	NP	H				+					-	
H	H	H	L	L	L		H					+				-	
H	H	H	L	H	L		H						+			-	
H	H	H	H	L	L		H							+		-	
X	X	X	X	X	L		L	Previous Channel Configuration									

(1) X = don't care, NP = negative pulse

### 3.2 Input Current

Due to the sampling nature of the analog inputs, short duration spikes of current enter the “+” input and exit the “-” input at the clock edges during the actual conversion. These currents decay rapidly and do not cause errors as the internal comparator is strobed at the end of a clock period. Bypass capacitors at the inputs will average these currents and cause an effective DC current to flow through the output resistance of the analog signal source. Bypass capacitors should not be used if the source resistance is greater than 1 k $\Omega$ .

### 3.3 Input Source Resistance

The limitation of the input source resistance due to the DC leakage currents of the input multiplexer is important. A worst-case leakage current of  $\pm 1 \mu\text{A}$  over temperature will create a 1 mV input error with a 1 k $\Omega$  source resistance. An op amp RC active low pass filter can provide both impedance buffering and noise filtering should a high impedance signal source be required.

## 4.0 OPTIONAL ADJUSTMENTS

### 4.1 Zero Error

The zero of the A/D does not require adjustment. If the minimum analog input voltage value,  $V_{\text{IN(MIN)}}$ , is not ground, a zero offset can be done. The converter can be made to output 0000 0000 digital code for this minimum input voltage by biasing any  $V_{\text{IN}}$  (-) input at this  $V_{\text{IN(MIN)}}$  value. This is useful for either differential or pseudo-differential modes of input channel configuration.

The zero error of the A/D converter relates to the location of the first riser of the transfer function and can be measured by grounding the  $V^-$  input and applying a small magnitude positive voltage to the  $V^+$  input. Zero error is the difference between actual DC input voltage which is necessary to just cause an output digital code transition from 0000 0000 to 0000 0001 and the ideal  $\frac{1}{2}$  LSB value ( $\frac{1}{2}$  LSB = 9.8 mV for  $V_{REF} = 5.000 V_{DC}$ ).

#### 4.2 Full-Scale

The full-scale adjustment can be made by applying a differential input voltage which is  $1 \frac{1}{2}$  LSB down from the desired analog full-scale voltage range and then adjusting the magnitude of the  $V_{REF}$  input for a digital output code changing from 1111 1110 to 1111 1111.

#### 4.3 Adjusting for an Arbitrary Analog Input Voltage Range

If the analog zero voltage of the A/D is shifted away from ground (for example, to accommodate an analog input signal which does not go to ground), this new zero reference should be properly adjusted first. A  $V_{IN} (+)$  voltage which equals this desired zero reference plus  $\frac{1}{2}$  LSB (where the LSB is calculated for the desired analog span,  $1 \text{ LSB} = \text{analog span}/256$ ) is applied to selected “+” input and the zero reference voltage at the corresponding “-” input should then be adjusted to just obtain the 00<sub>HEX</sub> to 01<sub>HEX</sub> code transition.

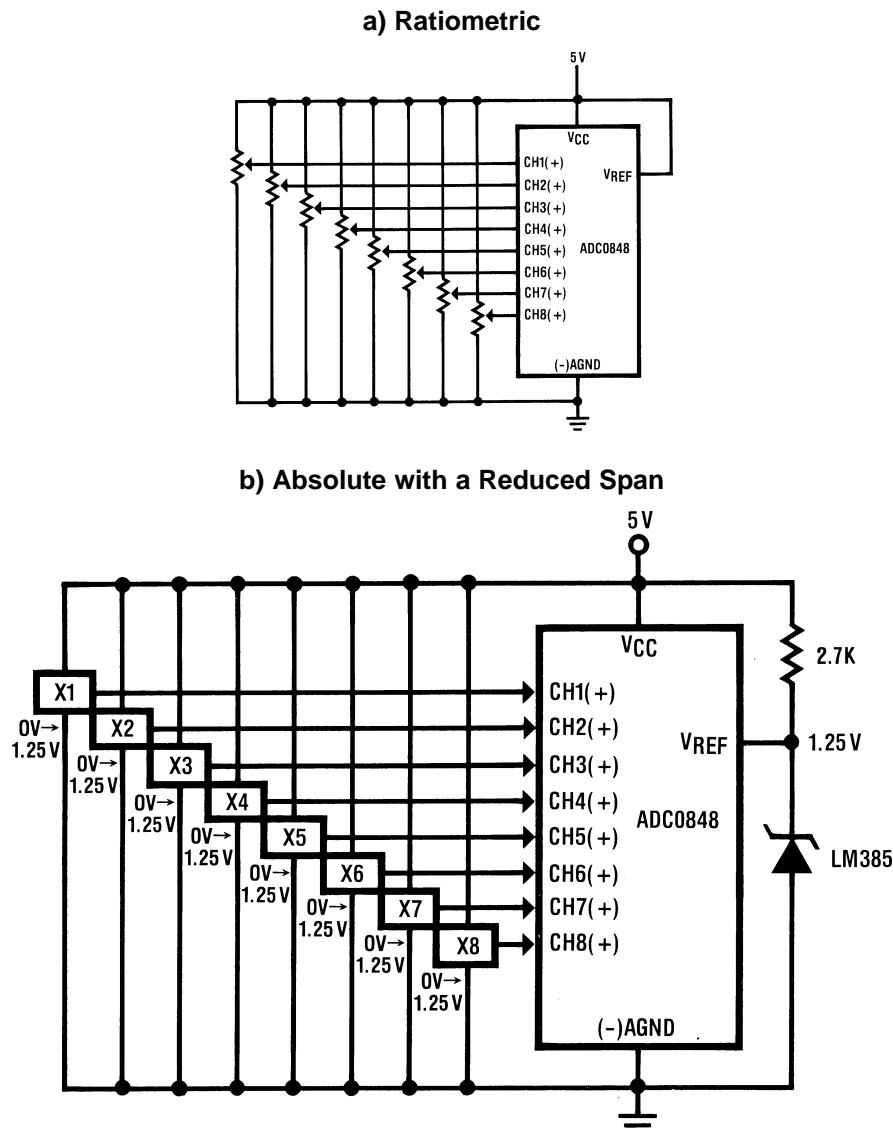


Figure 10. Referencing Examples

The full-scale adjustment should be made [with the proper  $V_{IN}(-)$  voltage applied] by forcing a voltage to the  $V_{IN}(+)$  input which is given by:

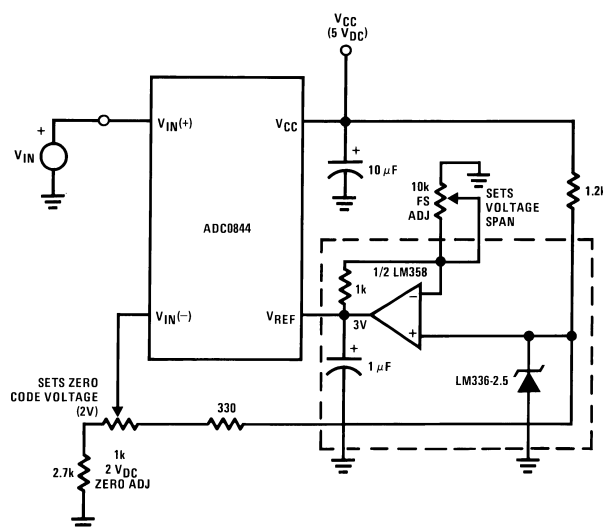
$$V_{IN}(+) \text{ fs adj} = V_{MAX} - 1.5 \left[ \frac{(V_{MAX} - V_{MIN})}{256} \right] \quad (1)$$

where  $V_{MAX}$ =the high end of the analog input range and  $V_{MIN}$ =the low end (the offset zero) of the analog range. (Both are ground referenced.)

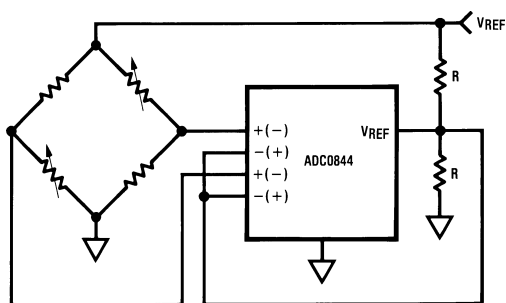
The  $V_{REF}$  (or  $V_{CC}$ ) voltage is then adjusted to provide a code change from  $FE_{HEX}$  to  $FF_{HEX}$ . This completes the adjustment procedure.

For an example see the Zero-Shift and Span Adjust circuit below.

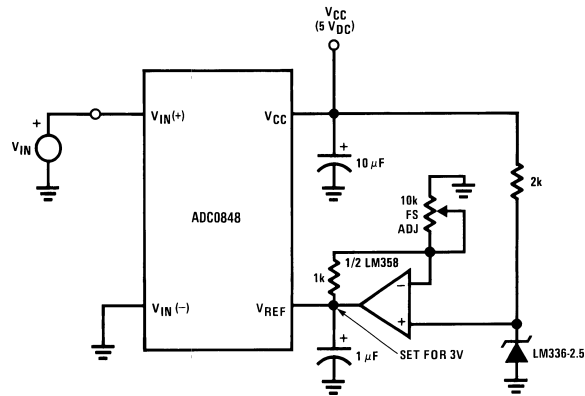
**Figure 11. Zero-Shift and Span Adjust ( $2V \leq V_{IN} \leq 5V$ )**



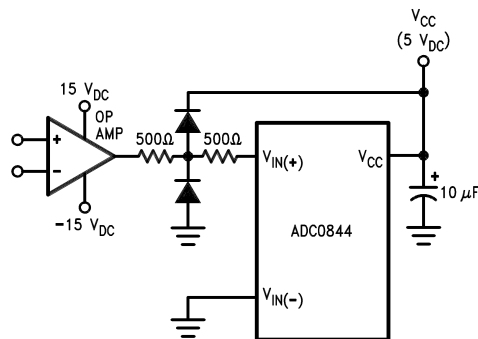
**Figure 12. Differential Voltage Input 9-Bit A/D**



**Figure 13. Span Adjust ( $0V \leq V_{IN} \leq 3V$ )**

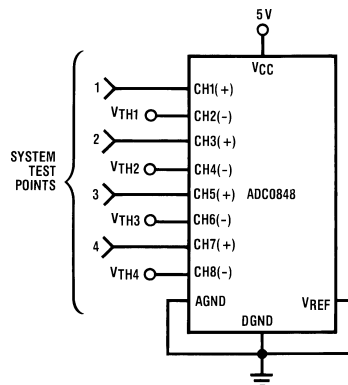


### Figure 14. Protecting the Input



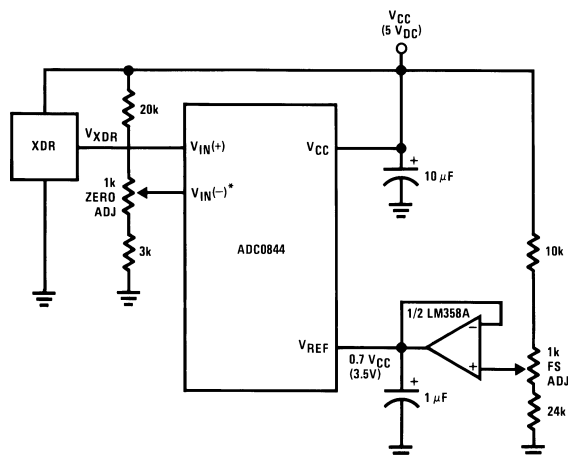
Diodes are 1N914

### Figure 15. High Accuracy Comparators



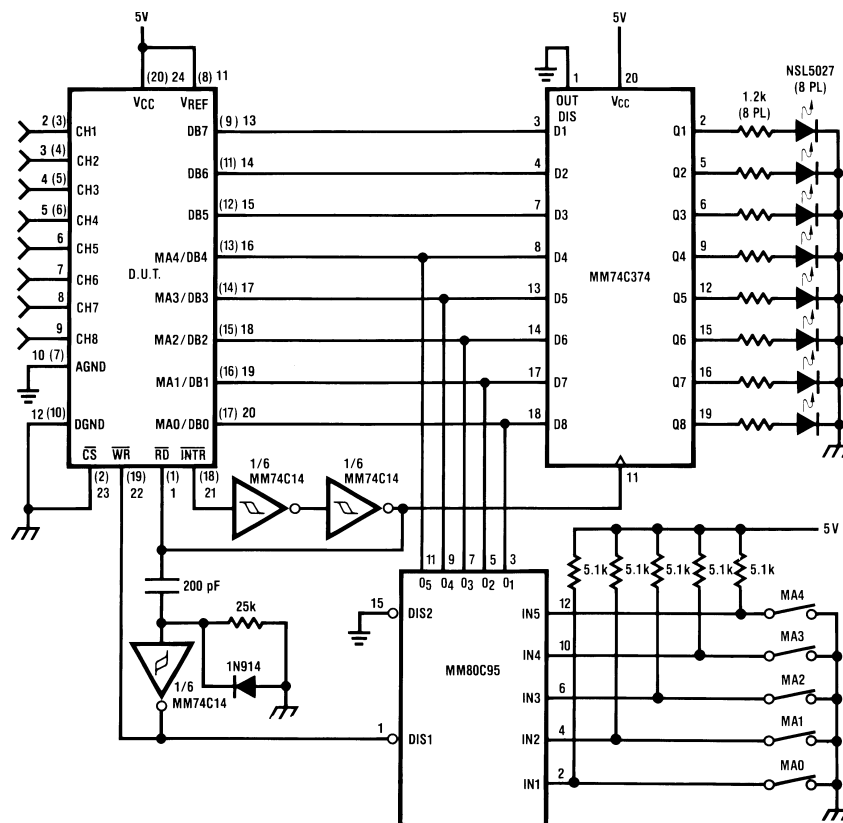
DO = all 1s if  $V_{IN(+)} > V_{IN(-)}$   
DO = all 0s if  $V_{IN(+)} < V_{IN(-)}$

### Figure 16. Operating with Automotive Ratiometric Transducers



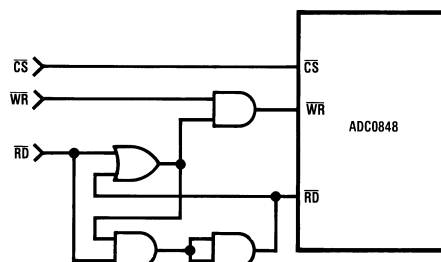
\*  $V_{IN(-)} = 0.15 V_{CC}$   
 $15\% \text{ of } V_{CC} \leq V_{XDR} \leq 85\% \text{ of } V_{CC}$

### Figure 17. A Stand Alone Circuit



**Note:** DUT pin numbers in parentheses are for ADC0844, others are for ADC0848.

**Figure 18. Start a Conversion without Updating the Channel Configuration**

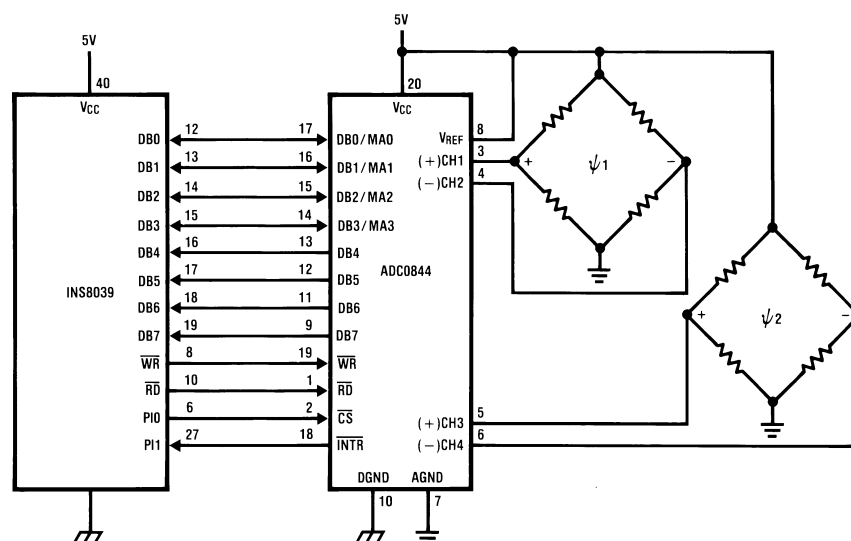


$\overline{\text{CS}} \cdot \overline{\text{WR}}$  will update the channel configuration and start a conversion.

**CS • RD** will read the conversion data and start a new conversion without updating the channel configuration.

Waiting for the end of this conversion is not necessary. A  $\overline{\text{CS}} \cdot \overline{\text{WR}}$  can immediately follow the  $\overline{\text{CS}} \cdot \overline{\text{RD}}$ .

**Figure 19. ADC0844—INS8039 Interface**



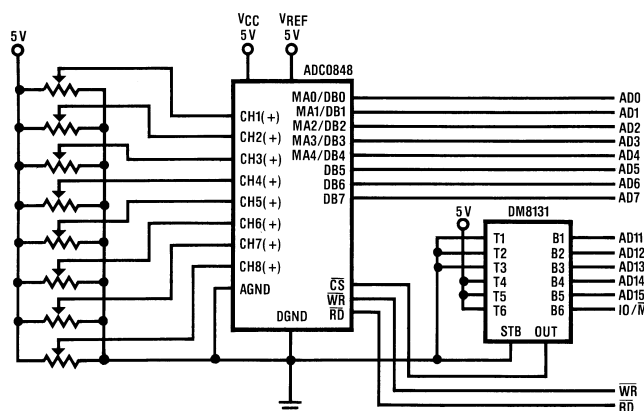
**Table 4. SAMPLE PROGRAM FOR ADC0844—INS8039 INTERFACE  
CONVERTING TWO RATIOMETRIC, DIFFERENTIAL SIGNALS**

			ORG	0H	
0000	04 10		JMP	BEGIN	;START PROGRAM AT ADDR 10
			ORG	10H	;MAIN PROGRAM
0010	B9 FF	BEGIN:	MOV	R1,#0FFH	;LOAD R1 WITH A UNUSED ADDR
					;LOCATION
0012	B8 20		MOV	R0,#20H	;A/D DATA ADDRESS
0014	89 FF		ORL	P1,#0FFH	;SET PORT 1 OUTPUTS HIGH
0016	23 00		MOV	A,00H	;LOAD THE ACC WITH A/D MUX DATA
					;CH1 AND CH2 DIFFERENTIAL
0018	14 50		CALL	CONV	;CALL THE CONVERSION SUBROUTINE
001A	23 02		MOV	A,#02H	;LOAD THE ACC WITH A/D MUX DATA
					;CH3 AND CH4 DIFFERENTIAL
001C	18		INC	R0	;INCREMENT THE A/D DATA ADDRESS
001D	14 50		CALL	CONV	;CALL THE CONVERSION SUBROUTINE
			;CONTINUE MAIN PROGRAM		
			;CONVERSION SUBROUTINE		
			;ENTRY:ACC—A/D MUX DATA		

**Table 4. SAMPLE PROGRAM FOR ADC0844—INS8039 INTERFACE  
CONVERTING TWO RATIOMETRIC, DIFFERENTIAL SIGNALS (continued)**

			;EXIT: ACC—CONVERTED DATA		
			ORG	50H	
0050	99 FE	CONV:	ANL	P1,#0FEH	;CHIP SELECT THE A/D
0052	91		MOVX	@R1,A	;LOAD A/D MUX & START CONVERSION
0053	09	LOOP:	IN	A,P1	;INPUT $\overline{\text{INTR}}$ STATE
0054	32 53		JB1	LOOP	;IF $\overline{\text{INTR}} = 1$ GOTO LOOP
0056	81		MOVX	A,@R1	;IF $\overline{\text{INTR}} = 0$ INPUT A/D DATA
0057	89 01		ORL	P1,&01H	;CLEAR THE A/D CHIP SELECT
0059	A0		MOV	@R0,A	;STORE THE A/D DATA
005A	83		RET		;RETURN TO MAIN PROGRAM

**Figure 20. I/O Interface to NSC800**



**Table 5. SAMPLE PROGRAM FOR ADC0848—NSC800 INTERFACE<sup>(1)</sup>**

0008		NCONV	EQU	16	
000F		DEL	EQU	15	;DELAY 50 $\mu$ sec CONVERSION
001F		CS	EQU	1FH	;THE BOARD ADDRESS
3C00		ADDTA	EQU	003CH	;START OF RAM FOR A/D
					;DATA
0000'	08 09 0A 0B	MUXDTA:	DB	08H,09H,0AH,0BH	;MUX DATA
0004'	0C 0D 0E 0F		DB	0CH,0DH,0EH,0FH	
0008'	0E 1F	START:	LD	C,CS	
000A'	06 16		LD	B,NCONV	
000C'	21 0000'		LD	HL,MUXDTA	
000F'	11 003C		LD	DE,ADDTA	
0012'	ED A3	STCONV:	OUTI		;LOAD A/D'S MUX DATA
					;AND START A CONVERSION
0014'	EB		EX	DE,HL	;HL=RAM ADDRESS FOR THE
					;A/D DATA
0015'	3E 0F		LD	A,DEL	
0017'	3D	WAIT:	DEC	A	;WAIT 50 $\mu$ sec FOR THE
0018'	C2 0013'		JP	NZ,WAIT	;CONVERSION TO FINISH
001B'	ED A2		INI		;STORE THE A/D'S DATA
					;CONVERTED ALL INPUTS?

(1) This routine sequentially programs the MUX data latch in the signal-ended mode. For CH1-CH8 a conversion is started, then a 50  $\mu$ s wait for the A/D to complete a conversion and the data is stored at address ADDTA for CH1, ADDTA + 1 for CH2, etc.

**Table 5. SAMPLE PROGRAM FOR ADC0848—NSC800 INTERFACE<sup>(1)</sup> (continued)**

001D'	EB		EX	DE,HL	
001E'	C2 000E'		JP	NZ,STCONV	;IF NOT GOTO STCONV
			END		

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
ADC0844CCN	ACTIVE	PDIP	NFH	20	18	TBD	Call TI	Level-1-NA-UNLIM	
ADC0844CCN/NOPB	ACTIVE	PDIP	NFH	20	18	Green (RoHS & no Sb/Br)	Call TI	Level-1-NA-UNLIM	
ADC0848BCV	ACTIVE	PLCC	FN	28	35	TBD	Call TI	Level-2A-245C-4 WEEK	
ADC0848BCV/NOPB	ACTIVE	PLCC	FN	28	35	Green (RoHS & no Sb/Br)	Call TI	Level-2A-245C-4 WEEK	
ADC0848BCVX	ACTIVE	PLCC	FN	28	750	TBD	Call TI	Level-2A-245C-4 WEEK	
ADC0848BCVX/NOPB	ACTIVE	PLCC	FN	28	750	Green (RoHS & no Sb/Br)	Call TI	Level-2A-245C-4 WEEK	
ADC0848CCN	ACTIVE	PDIP	NAM	24	15	TBD	Call TI	Level-1-NA-UNLIM	
ADC0848CCN/NOPB	ACTIVE	PDIP	NAM	24	15	Pb-Free (RoHS)	Call TI	Level-1-NA-UNLIM	
ADC0848CCV	ACTIVE	PLCC	FN	28	35	TBD	Call TI	Level-2A-245C-4 WEEK	
ADC0848CCV/NOPB	ACTIVE	PLCC	FN	28	35	Green (RoHS & no Sb/Br)	Call TI	Level-2A-245C-4 WEEK	
ADC0848CCVX	ACTIVE	PLCC	FN	28	750	TBD	Call TI	Level-2A-245C-4 WEEK	
ADC0848CCVX/NOPB	ACTIVE	PLCC	FN	28	750	Green (RoHS & no Sb/Br)	Call TI	Level-2A-245C-4 WEEK	

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

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**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

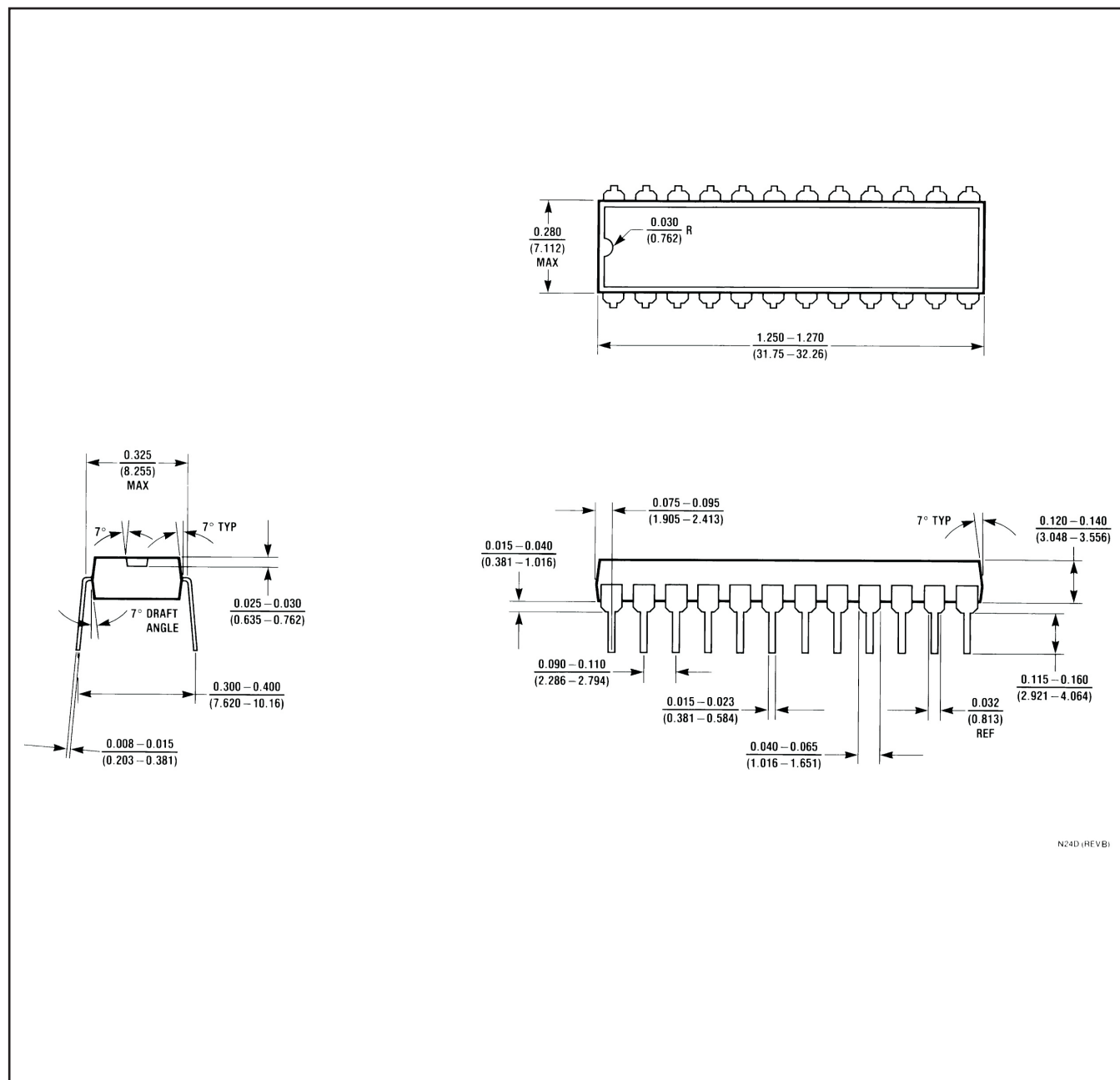
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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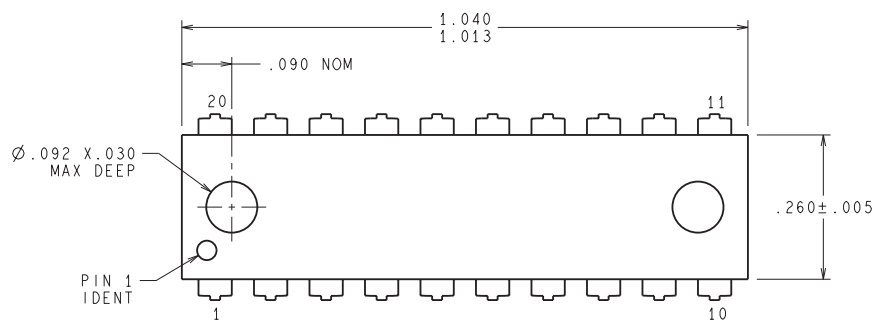
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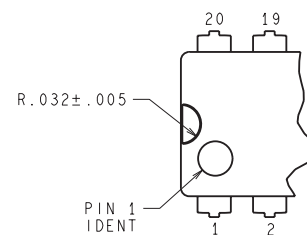


N24D (REV B)

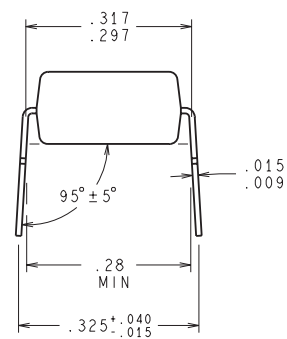
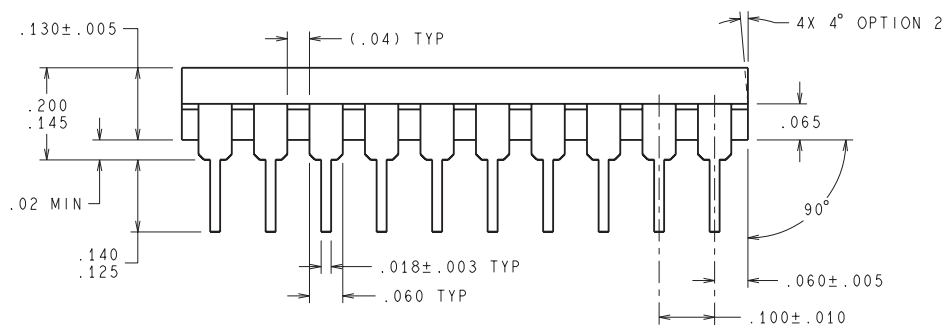
NFH0020A



OPTION 1



OPTION 2

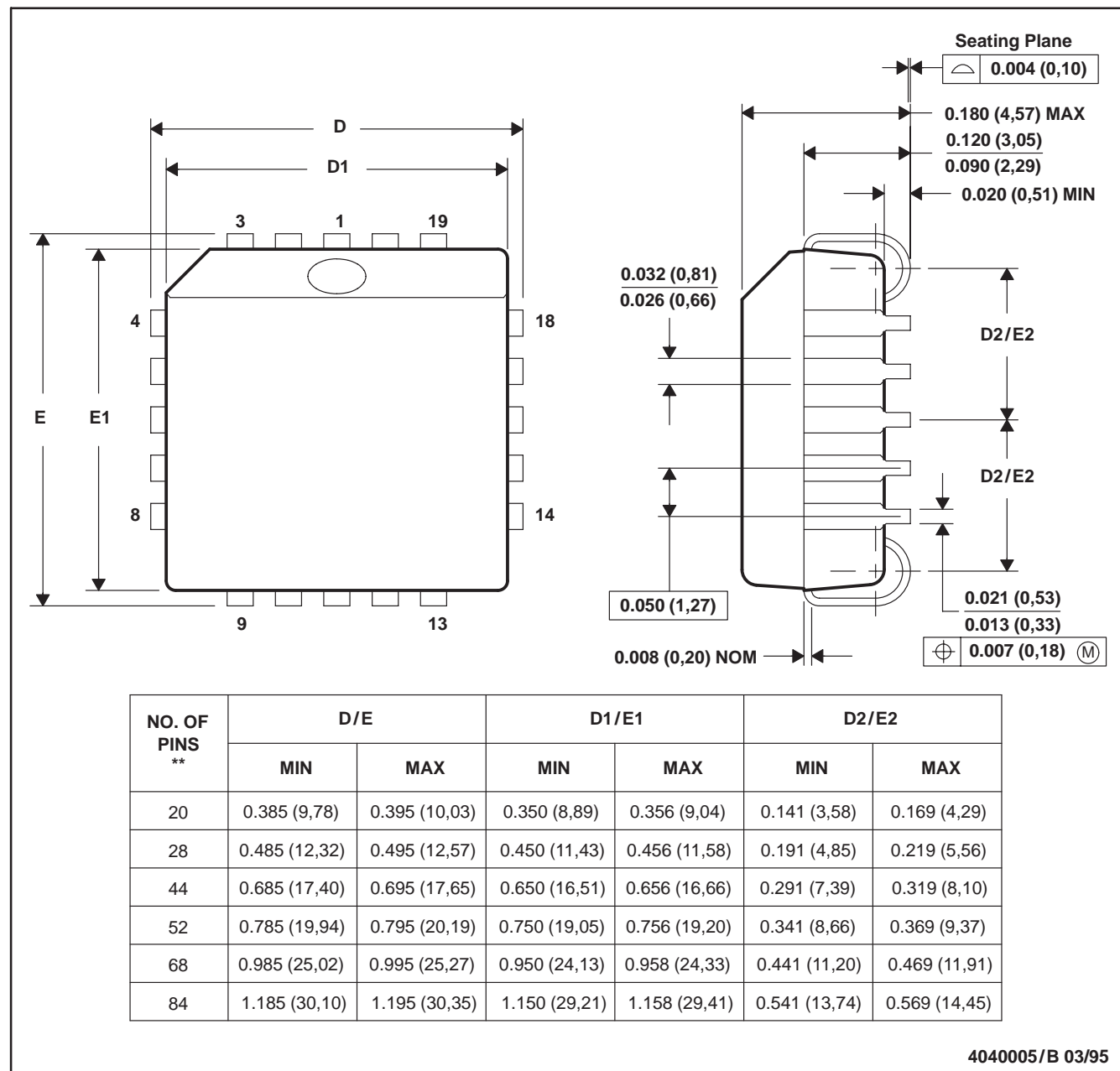


N20A (Rev G)

FN (S-PQCC-J\*\*)

PLASTIC J-LEADED CHIP CARRIER

20 PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Falls within JEDEC MS-018

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